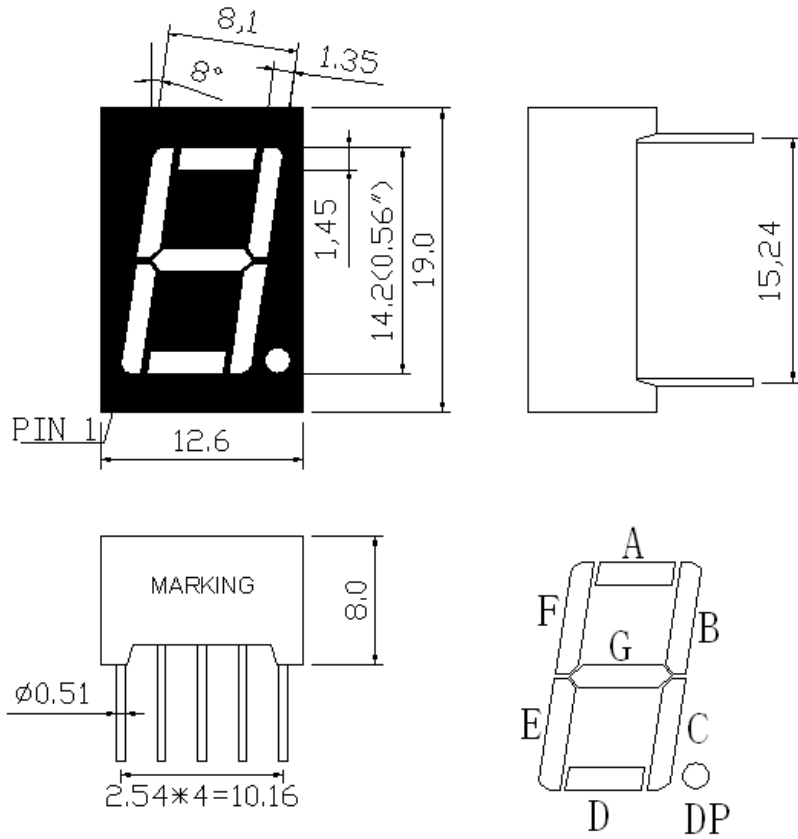
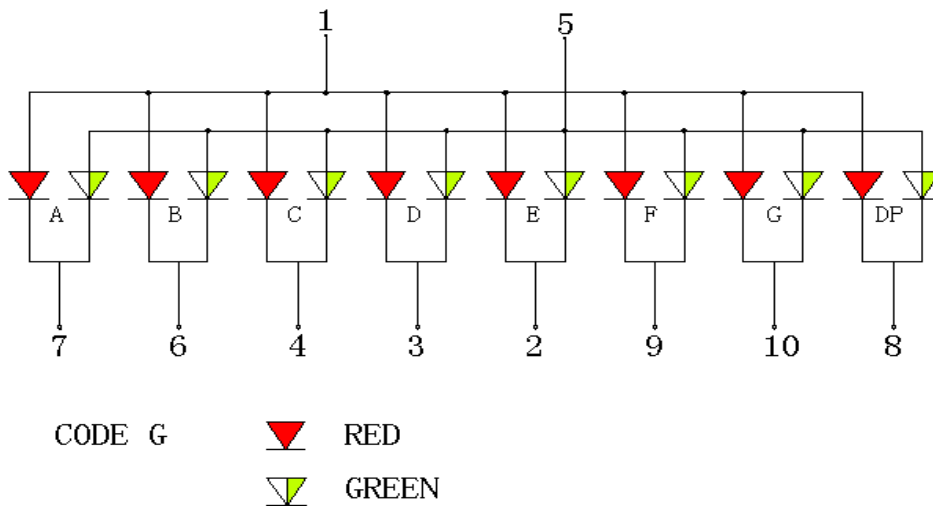


P/N: E10561B-G-UR3K2-0-W

PACKAGE DIMENSION



INTERNAL CIRCUIT DIAGRAM



NOTES:

1. All dimensions are in millimeter;
2. Tolerance is ± 0.25 mm unless other specified;
3. Pin length, housing color, marking no & circuit diagram can be customized;
4. Specifications are subject to change without notice.

P/N: E10561B-G-UR3K2-0-W

CHARACTERS

Chip Material: AlGaInP / GaAs Yellow Green LED Chip

ABSOLUTE MAXIMUM RATINGS (Ta = 25)

PARAMETER	SYMBOL	MAXIMUM RATING	UNIT
Power Dissipation	PD	65	mW
Peak Forward Current (1/10 Duty Cycle, 0.1 Ms Pulse Width)	IPEAK	100	mA
DC Forward Current	IF	25	mA
Reverse Voltage	VR	5	V
Operating Temperature Range	Topr / Tstg	-40°C to +85°C	
Storage Temperature Range	Topr / Tstg	-40°C to +100°C	

ELECTRICAL OPTICAL CHARACTER AND CURVES (Ta = 25)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION (Per Chip)
Forward Voltage	VF	-	2.20	2.60	V	IF =20mA
Luminous Intensity	Iv	12	14	-	mcd	IF =20mA
Peak Emission Wavelength	λp	-	575	-	nm	IF =20mA
Dominant Emission Wavelength	λd	565	570	575	nm	IF =20mA
Spectral Line Half-Width	Δλ1/2	-	20	-	nm	IF =20mA
Reverse Current	IR	-	15	-	uA	VR = 5V

Note:

- Luminous intensity tolerance is ±10%;**
- Dominant Emission Wavelength tolerance is ±5%.**

P/N: E10561B-G-UR3K2-0-W

TYPICAL ELECTRO-OPTICAL CHARACTERISTIC CURVE

FIG. 1 Forward Current Vs. Forward Voltage

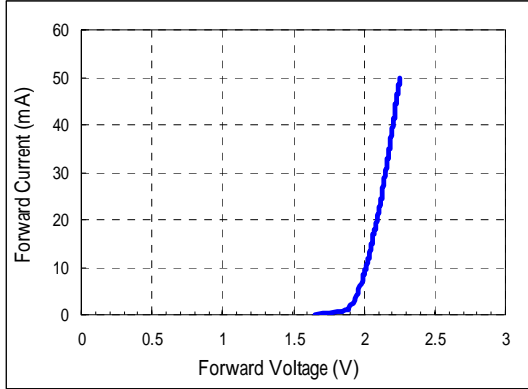


FIG. 2 Relative Intensity Vs. Forward Current

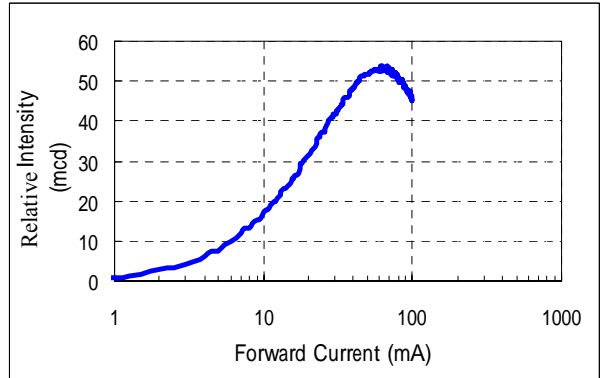


FIG. 3 Forward Voltage Vs. Temperature

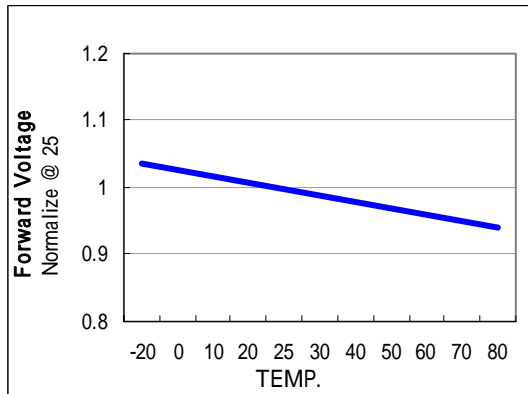


FIG. 4 Relative Intensity Vs. Temperature

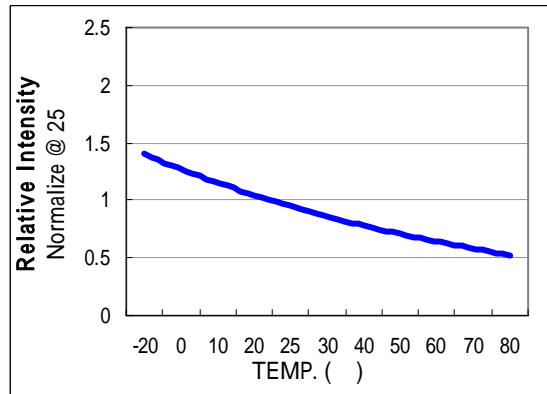
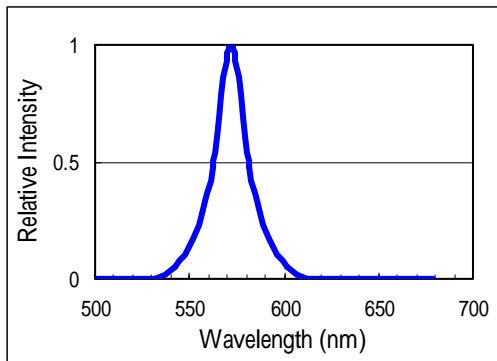


FIG. 5 Relative Intensity Vs. Wavelength



P/N: E10561B-G-UR3K2-0-W

CHARACTERS

Chip Material: AlGaInP / GaAs Ultra Bright Red LED Chip



ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C)

PARAMETER	SYMBOL	MAXIMUM RATING	UNIT
Power Dissipation	PD	72	mW
Peak Forward Current (1/10 Duty Cycle, 0.1 Ms Pulse Width)	IPEAK	90	mA
DC Forward Current	IF	30	mA
Reverse Voltage	VR	5	V
Operating Temperature Range	Topr / Tstg	-40°C to +85°C	
Storage Temperature Range	Topr / Tstg	-40°C to +100°C	

ELECTRICAL OPTICAL CHARACTER AND CURVES (Ta = 25 °C)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION (Per Chip)
Forward Voltage	VF	-	2.05	2.40	V	IF =20mA
Luminous Intensity	Iv	34	38	56	mcd	IF =20mA
Peak Emission Wavelength	λp	-	645	-	nm	IF =20mA
Dominant Emission Wavelength	λd	628	635	638	nm	IF =20mA
Spectral Line Half-Width	Δλ1/2	-	20	-	nm	IF =20mA
Reverse Current	IR	-	-	10	uA	VR = 5V

Note:

- Luminous intensity tolerance is ±10%;**
- Dominant Emission Wavelength tolerance is ±5%.**

P/N: E10561B-G-UR3K2-0-W

TYPICAL ELECTRO-OPTICAL CHARACTERISTIC CURVE

FIG. 1 Forward Current Vs. Forward Voltage

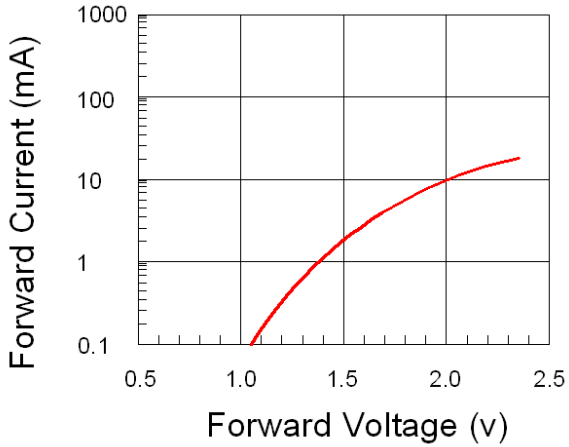


FIG. 2 Relative Intensity Vs. Forward Current

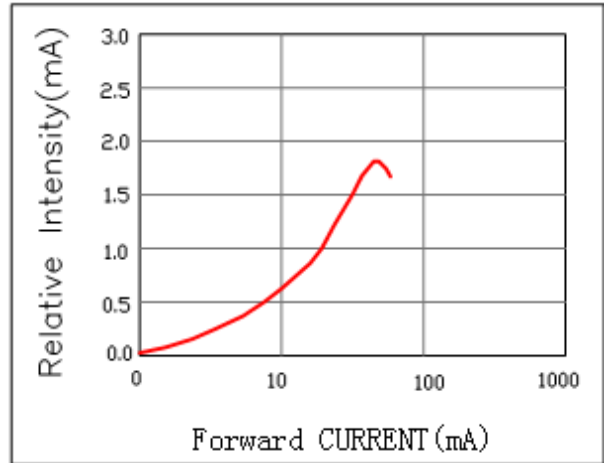


FIG. 3 Forward Voltage Vs. Temperature

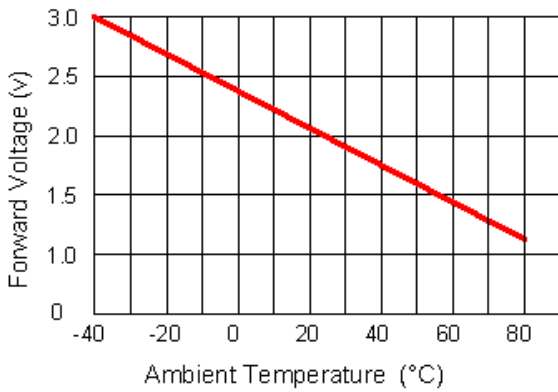


FIG. 4 Relative Intensity Vs. Temperature

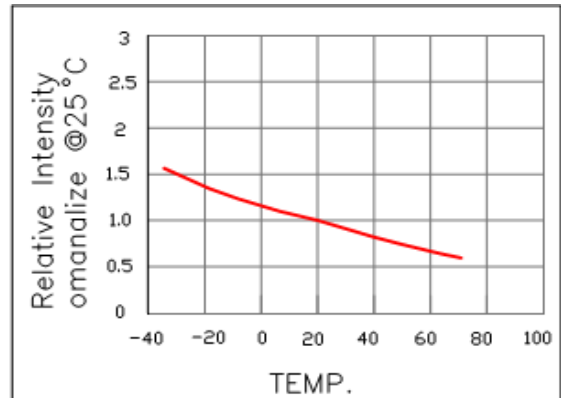
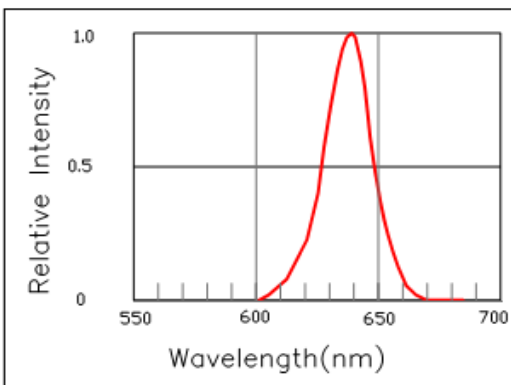
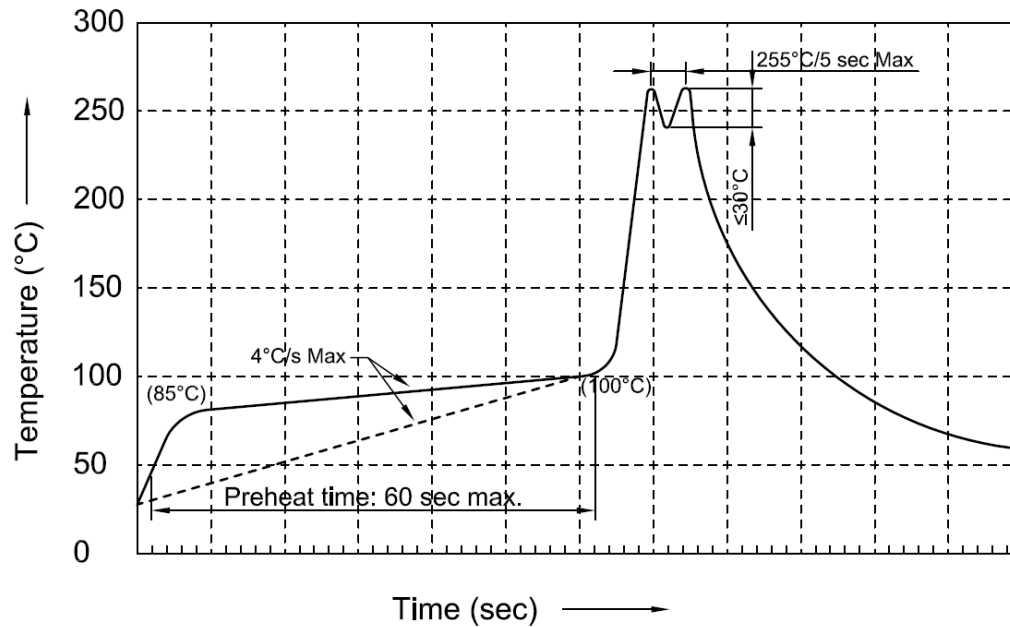


FIG. 5 Relative Intensity Vs. Wavelength



P/N: E10561B-G-UR3K2-0-W

Recommended Wave Soldering Profiles:



Notes:

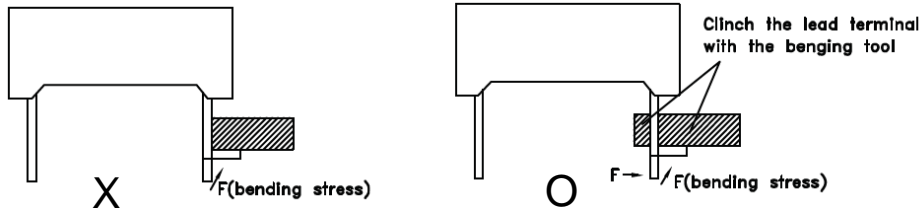
1. Recommend pre-heat temperature of 105 or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260 .
2. Peak wave soldering temperature between 245-255 for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85 .
4. Fixtures should not apply stress on the component when mounting and soldering process.
5. More than one wave soldering is not allowed.

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THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming

Bend the component leads by hand without proper tools is not allowed. The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.

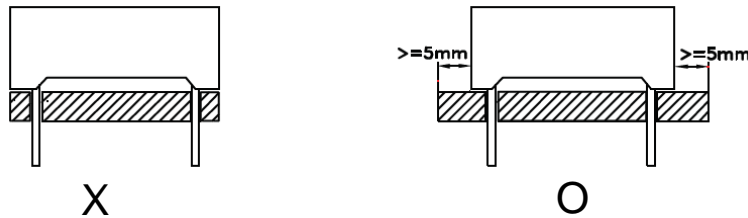


Installation

1. Do not apply stress to the lead terminals.
2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.



1. The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.



Storage

1. The LEDs should be stored at temp. ≤ 30 & RH. $\leq 70\%$ after being shipped from TOYO and the storage life limits are 3 months. If the LEDs are stored for 3 months or more, they can be stored for a year in a sealed container with a nitrogen atmosphere and absorbent material.
2. Please avoid rapid transitions in ambient temperature, especially in high humidity environments where condensation can occur.

Soldering General Notes

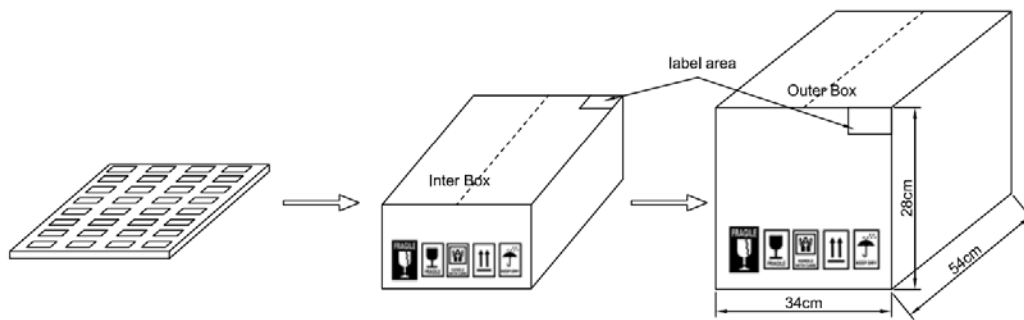
1. Through-hole displays are incompatible with reflow soldering.
2. If components will undergo multiple soldering processes where the components may be subjected to intense heat, please check with TOYO for compatibility.

Cleaning

1. Mild "no-clean" fluxes are recommended for use in soldering.
2. If cleaning is required, TOYO recommends to wash components enclosure with water only. Do not use organic solvents for cleaning, because they may damage the plastic parts. And the devices should not be washed for more than one minute.

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PACKING & LABEL SPECIFICATIONS



Notes:

1. All dimension are in millimeter;
2. Tolerance is $\pm 0.25\text{mm}$ unless otherwise specified.
3. Not recommend to solder within 3mm from the resin.
4. Any kind of LEDs can be made in taped.

P/N: E10561B-G-UR3K2-0-W

REVISION HISTORY

DATE	REVISION CONTENTS	VERSION
2016-03-07	New	A